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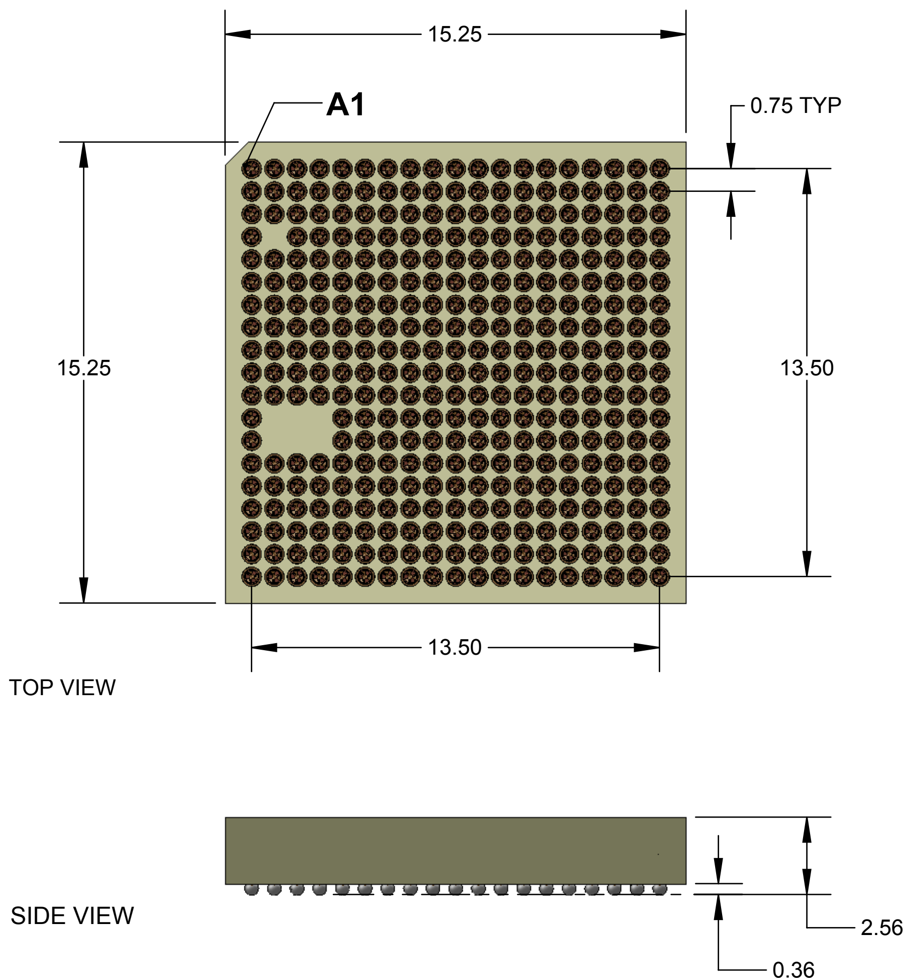
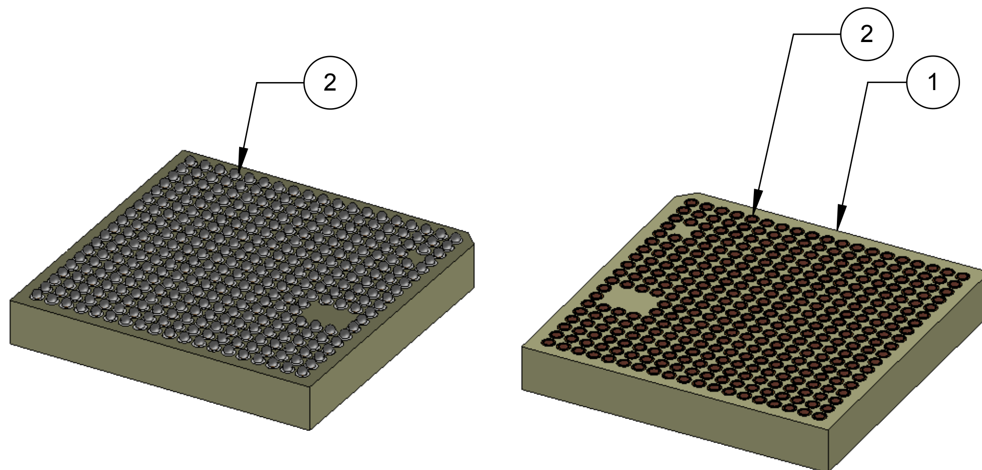
U.S. Patent No. 8,091,222 B2





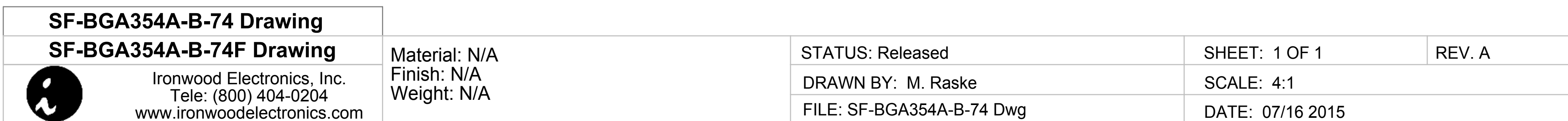
ITEM NO.	DESCRIPTION	Material
1	non-clad substrate; 15.254mm sq., 19x19 array, 0.75mm pitch, BGA354	High temperature substrate
2	P-S527A, 0.8mm Giga-snaP receptacle	Shell: Brass Alloy 360; 0.25µm [10µ"] Au over 2.54 µm [100µ"] Ni finish Contact: BeCu Alloy 172; 0.25µm [10µ"] Au over 1.27 µm [50µ"] Ni finish
3	Solder Ball, 0.4572mm dia	**SEE TABLE**

PART NO. SUFFIX	SOLDER BALL ALLOY
-74	Sn63Pb37
-74F*	Sn96.5Ag3.0Cu0.5
*RoHS Compliant	

Description: Giga-snaP BGA SMT Foot BGA354 19x19 array 0.75 pitch 15.254 sq.mm

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.



SF-BGA354A-B-74 Drawing

SF-BGA354A-B-74F Drawing

Ironwood Electronics, Inc.
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Material: N/A
Finish: N/A
Weight: N/A

STATUS: Released	SHEET: 1 OF 1	REV. A
DRAWN BY: M. Raske	SCALE: 4:1	
FILE: SF-BGA354A-B-74 Dwg	DATE: 07/16 2015	